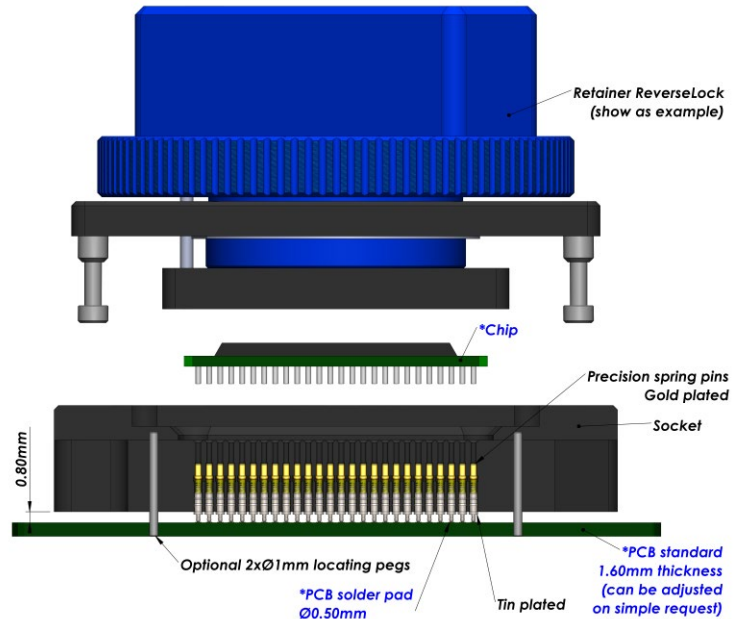
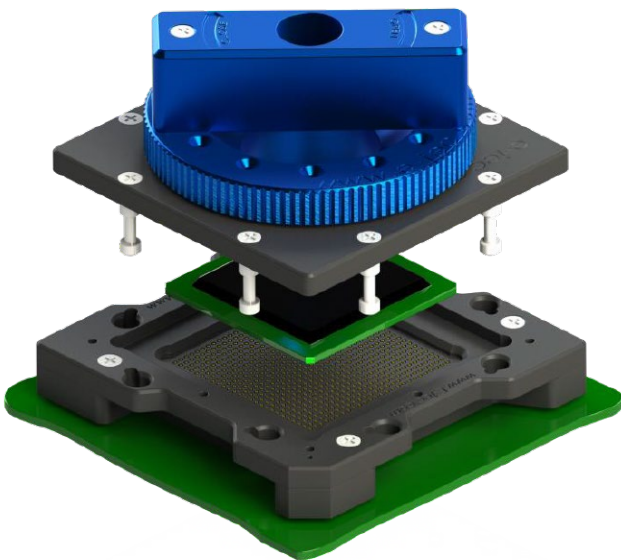
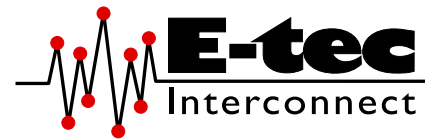


Standard SMT soldering Test Socket

For CGA / PGA / PGI Package

1.00 mm pitch (from 1.00 mm up to 1.26 mm)



E-tec Interconnect AG is the world leading Test socket manufacturer

The SMT socket uses the same footprint as your chip. Socket is simply placed and reflowed onto the PCB in the same way as the chip and it only requires a small amount of additional board space. SMT type sockets are available with all retention systems. We aim to solve your requirements. Please note, we will always request the chip data to ensure we offer a compatible socket. For SMT sockets in general, E-tec Interconnect AG recommends the use of locating pegs, which can be soldered to the PCB for added mechanical strength.

Specifications contact type code 1030			
Application	Surface mouting	Force	25 gr
Mounting	SMT	Current rating	1.8 A
Bandwidth (GHz@-1dB)	2.8(6.6) GHz	Capacitance pF	0.62 pF
Contact resistance	<100mOhm	Inductance nH	1.97 nH
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C
PCB tip shape	SMT	Mating cycles	100 K

How to order

CU # #### -1030 - ##### 95 #

Shape of tip

U : Concave

Options:

P : Pointed

Nbr of contacts

Depends on ballcount of chip

Contact type

30 : Standard SMT – Dimension A = 0.80 mm

Plating

95 : Tin / Gold

Other on request

Option code (see page 16-19)

D : Dead bug

M : Multi frames

U : Multi packages

C : Converter plate

S : Custom opening slot

L : Locating pegs

H : Heatsink

F : Fan + Heatsink

P : Thermal drain pad

W : Transparent lid

I : Steel retention lid

B : Aluminium retention lid

G : Handling button

Retention frame type (Lid) (see page 12-15)

W: TwistLock

F : FastLock

B : SpringLock

H : Open Clamshell Alu (<200 contacts)

J : Clamshell Alu (>200 contacts)

L : Open Lever Clamshell Alu (>200 contacts)

S : ScrewLock

Q : Open QuickLock (<200 contacts)

D : QuickLock (>200 contacts)

M : Injection Molded ClamShell

R : ReverseLock

T : SlimLock

Grid code / Config. code

Will be given by the factory after receipt of the chip datasheet

